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# FDS6681Z

## 30 Volt P-Channel PowerTrench<sup>®</sup> MOSFET General Description

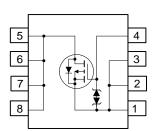
This P-Channel MOSFET is produced using ON Semiconductor's advanced PowerTrench<sup>®</sup> process that has been especially tailored to minimize the on-state resistance.

This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery Packs.

#### Features

- -20 A, -30 V.  $R_{DS(ON)} = 4.6 \text{ m}\Omega @ V_{GS} = -10 \text{ V}$  $R_{DS(ON)} = 6.5 \text{ m}\Omega @ V_{GS} = -4.5 \text{ V}$
- + Extended  $V_{\text{GSS}}$  range (–25V) for battery applications
- HBM ESD protection level of 8kV typical (note 3)
- High performance trench technology for extremely low R<sub>DS(ON)</sub>
- High power and current handling capability
- Termination is Lead-free and RoHS Compliant





### Absolute Maximum Ratings $T_A=25^{\circ}C$ unless otherwise noted

Symbol		Parameter		Ratings	Units
V <sub>DSS</sub>		ource Voltage		-30	V
V <sub>GSS</sub>	Gate-So	urce Voltage		±25	V
I <sub>D</sub>	Drain Cu	urrent – Continuous	(Note 1a)	-20	A
		- Pulsed		-105	
<b>&gt;</b> <sub>D</sub>	Power D	issipation for Single Operation	(Note 1a)	2.5	W
			(Note 1b)	1.2	
			(Note 1c)	1.0	
T <sub>J</sub> , T <sub>stg</sub>	Operatin	g and Storage Junction Temper	ature Range	-55 to +150	°C
Therma	al Chara	acteristics			
		acteristics Resistance, Junction-to-Ambier	nt (Note 1a)	50	°C/W
Therma R <sub>0JA</sub> R <sub>0JC</sub>	Thermal		Note 1a) (Note 1)	50 25	°C/W
ર <sub>θJA</sub> ર <sub>θJC</sub>	Thermal Thermal ge Mark	Resistance, Junction-to-Ambier Resistance, Junction-to-Case ing and Ordering Int	(Note 1)		

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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics				1	
BV <sub>DSS</sub>	Drain–Source Breakdown Voltage	$V_{GS} = 0 V$ , $I_D = -250 \mu A$	-30			V
ΔBV <sub>DSS</sub> ΔTJ	Breakdown Voltage Temperature Coefficient	$I_D = -250 \ \mu$ A, Referenced to 25°C		-26		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -24 V, V_{GS} = 0 V$			-1	μA
I <sub>GSS</sub>	Gate-Body Leakage	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μA
On Chara	Acteristics (Note 2)					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	-1	-1.8	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \ \mu$ A, Referenced to $25^{\circ}$ C		6		mV/°C
$R_{\text{DS(on)}}$	Static Drain–Source On–Resistance	$ \begin{array}{l} V_{GS} = -10 \ V, \ \ I_D = -20 \ A \\ V_{GS} = -4.5 \ V, \ \ I_D = -17 \ A \\ V_{GS} = -10 \ V, \ \ I_D = -20 \ A, \\ T_J = 125^{\circ} C \end{array} $		3.8 5.2 5.0	4.6 6.5 6.3	mΩ
<b>g</b> <sub>FS</sub>	Forward Transconductance	$V_{DS} = -5 V$ , $I_D = -20 A$		79		S
Dvnamic	Characteristics					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -15 V$ , $V_{GS} = 0 V$ ,		7540		pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz		1400		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	7		1120		pF
Switchin	G Characteristics (Note 2)					
t <sub>d(on)</sub>	Turn–On Delay Time			20	35	ns
tr	Turn–On Rise Time			9	18	ns
t <sub>d(off)</sub>	Turn–Off Delay Time	7		660	1060	ns
t <sub>f</sub>	Turn–Off Fall Time	7		380	610	ns
Q <sub>g(TOT)</sub>	Total Gate Charge at $V_{GS} = -10V$	$V_{DS} = -15 \text{ V}, I_{D} = -20 \text{ A}$		185	260	nC
Q <sub>g(TOT)</sub>	Total Gate Charge at $V_{GS} = -5V$			105	150	nC
$Q_{gs}$	Gate-Source Charge			26		nC
Q <sub>gd</sub>	Gate-Drain Charge			47		nC

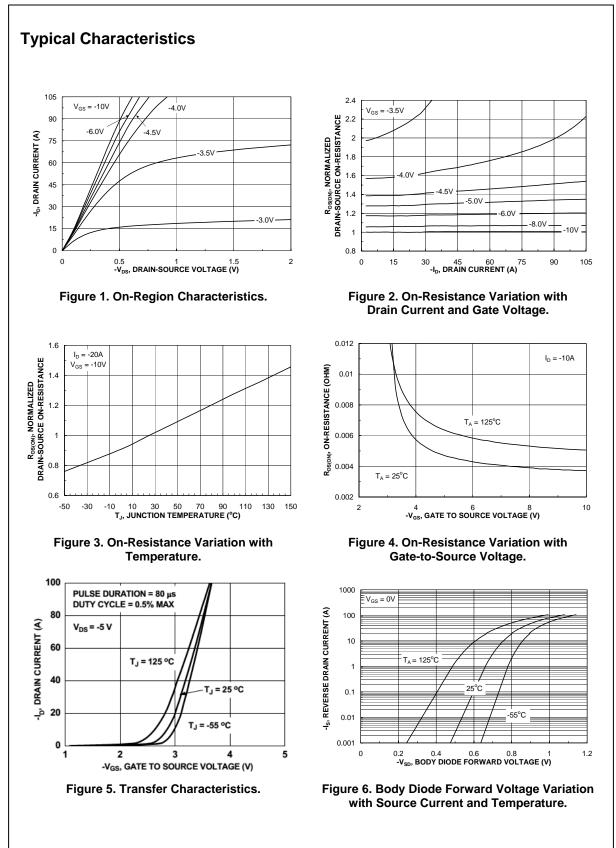
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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-So	ource Diode Characteristics a	nd Maximum Ratings				
Is	Maximum Continuous Drain-Source	Diode Forward Current			-2.1	А
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 V$ , $I_S = -2.1 A$ (Note 2)		-0.7	-1.2	V
t <sub>RR</sub>	Reverse Recovery Time	$I_{F} = -20 A,$		125		ns
Q <sub>RR</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/µs (Note 2)		94		nC
. R <sub>eja</sub> is the su	im of the junction-to-case and case-to-ambient them	mai resistance where the case thermal reference is	defined as	the solder n	nounting su	inface of the
drain pins. R ແມ	$R_{\theta,\text{DC}}$ is guaranteed by design while $R_{\theta,\text{CA}}$ is determine	ed by the user's board design.			-	

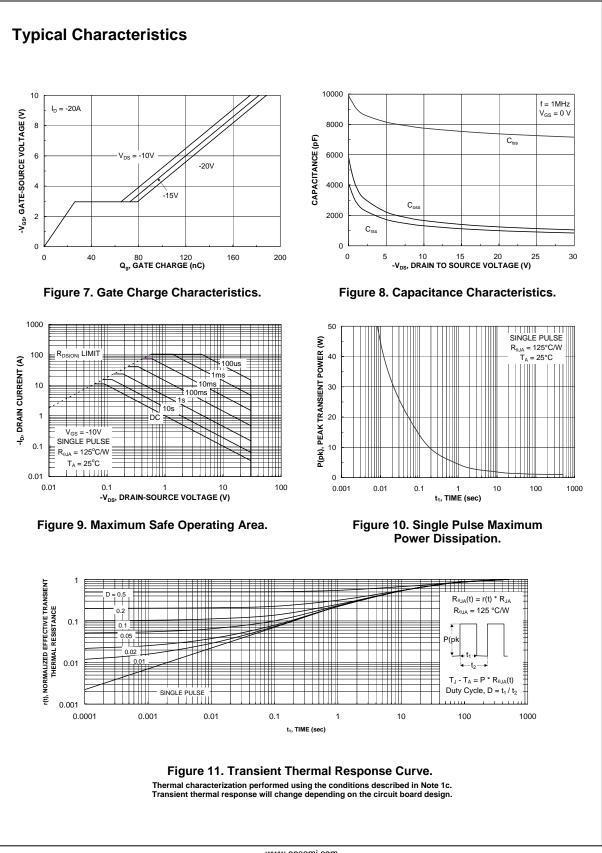
Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300 $\mu s,$  Duty Cycle < 2.0%

3. The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.



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